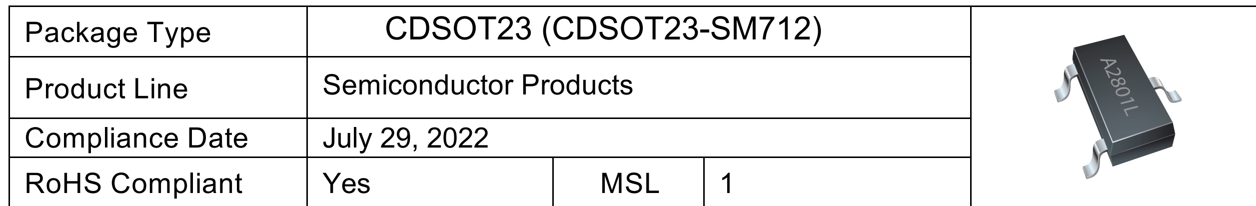
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-SM712)		
Product Line	Semiconductor Products		
Compliance Date	July 29, 2022		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.0051221	Amorphous Silica	60676-86-0	87.6000	46.24895	49.68122
				Epoxy Resin A	Proprietary	4.9000	1.27741	
				Epoxy Resin B	29690-82-2	4.0000	1.15051	
				Phenol Resin	Proprietary	3.0000	0.78209	
				Carbon Black	1333-86-4	0.5000	0.22226	
2	Leadframe	Copper Alloy	0.0039424	Copper	7440-50-8	97.1003	37.21385	38.23847
				Iron	7439-89-6	2.2889	0.77126	
				Phosphorus	7723-14-0	0.0199	0.00156	
				Zinc	7440-66-6	0.0995	0.03046	
				Lead	7439-92-1	0.0100	0.00484	
				Silver	7440-22-4	0.4814	0.21649	
3	Chip	Silicon	0.0007400	Silicon	7440-21-3	90.6836	6.50867	7.17734
				Nickel	7440-02-0	6.0672	0.43546	
				Aluminum	7429-90-5	2.8736	0.20625	
				Gold	7440-57-5	0.3756	0.02696	
4	Die Attach	Silver Epoxy	0.0002429	Silver	7440-22-4	75.0000	2.11489	2.35620
				Epoxy resin	9003-36-5	19.9000	0.21082	
				1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	3.0000	0.00887	
				Aromatic polyamine	Proprietary	2.0000	0.02126	
				Adipic acid	124-04-9	0.1000	0.00037	
5	Bond Wires	Copper	0.0000241	Copper	7440-50-8	98.7000	0.22947	0.23353
				Non - Cu element	Proprietary	1.3000	0.00406	
6	Lead Finish	Matte Tin	0.0002385	Tin	7440-31-5	100.0000	2.31324	2.31324
		Total Weight	0.010310					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

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